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PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

July 29, 2009

Applicant: Chisato HOSHINO

Title: THERMAL CONDUCTIVE SILICONE COMPOSITION

Serial No.: 10/567 587

Group: 1796

Confirmation No.: 2543

Filed: August 24, 2006

Examiner: Ojurongbe

International Application No.: PCT/JP2004/014679

International Filing Date: September 29, 2004

Atty. Docket No.: 3400.P1429US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

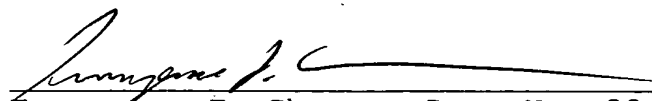
For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(4 - 20 = 0)		x \$ 52.00		x \$ 26.00	
Indep. Claims	(1 - 3 = 0)		x \$220.00		x \$110.00	
[] Multiple Dep. Claim			+ \$390.00		+ \$195.00	
* * * TOTAL FILING FEE * * *						\$ 0.00

[] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

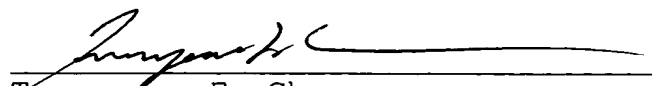
[] A Check for \$ is enclosed to cover fees.

[X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

TFC/smd


Terryence F. Chapman Reg. No. 32 549-----
CERTIFICATE OF MAILINGI hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on July 29, 2009.

130.10/08


Terryence F. Chapman